

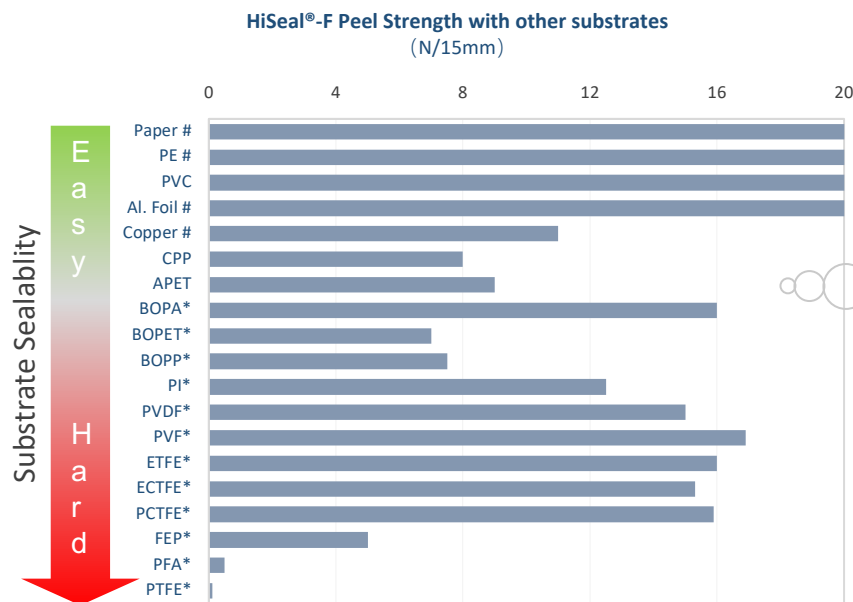
HiSeal®-F Heat Seal Film

HiSeal®-F film is specially developed to solve the adhesion challenges in packaging and electronics. It is a perfect medium to heat seal those non-sticking materials such as **PP, PET, PI** and **fluoropolymer films (ETFE, ECTFE, FEP, PVDF, etc.)**, let alone aluminum or copper foils.

i Features & Benefits:

1. Effective adhesion to non-sticking materials such as **PP, PET, PI** and **fluoropolymer films**.
2. Simple heat seal or high frequency welding process, no environmental concerns of solvent coating.
3. Reactive polymer bonding with high peel strength and reliability. High flexibility for bending.
4. Wide heat seal temperature window for various materials.

i HiSeal®-F Heat Seal Tests:



Very Important: Please consult Visualplas support on HiSeal®-F selection, substrate treatment and process conditions based on your substrates and applications.

Test Method : Hot press above substrates/ HiSeal®-F /Al. Foil (or PVC sheet) , 25 micron HiSeal® film is used. Heat press temperatures vary from 100°C to 230°C depending on substrates chemistry and thickness; pressure 0.5Mpa. Test peel strength after 24 hours ambient cooling.

Note : # inherent fracture occurred during peel test. Value is estimated.

Note : * Substrate surfaces are corona treated.

i HiSeal®-F Film Datasheet

Properties	Typical Value	Unit	Test Method
Thickness	25, 50	Micron	microcalliper
Appearance	Transparent	-	By Visual
Hardness	64	Shore A	ASTM D 2240
Elongation	1000	%	ASTM D 638
Flex modulus	<28	Mpa	ASTM D 638



i HiSeal®-F Film Storage

HiSeal®-F Film is heat active, suggest to store below 50°C and keep package sealed to avoid moisture.